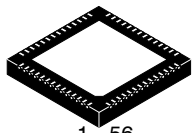# MECHANICAL CASE OUTLINE
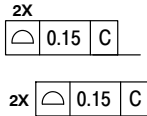## PACKAGE DIMENSIONS

ON Semiconductor®
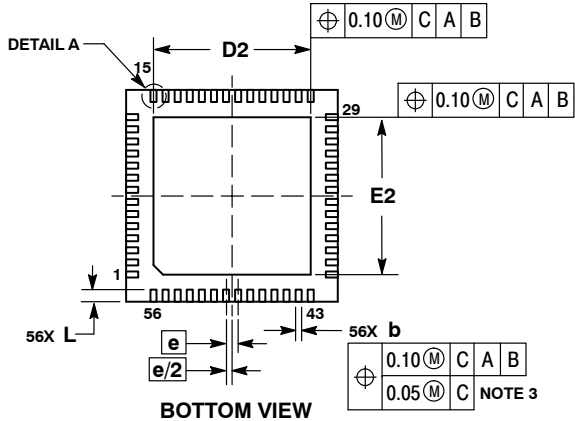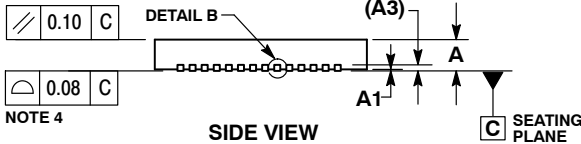
WQFN56 7x7, 0.4P
CASE 510BD
ISSUE O

DATE 29 JAN 2013

1   56
SCALE 2:1

PIN 1
INDICATOR

D | A B

E

2X
△ | 0.15 | C

2X △ | 0.15 | C

TOP VIEW

L   L

L1
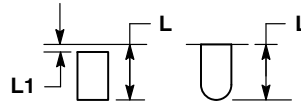
DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

EXPOSED Cu   MOLD CMPD
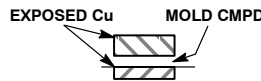
DETAIL B
ALTERNATE
CONSTRUCTION

⫽ | 0.10 | C   DETAIL B   (A3)

A

△ | 0.08 | C
NOTE 4   **SIDE VIEW**   A1

C SEATING PLANE

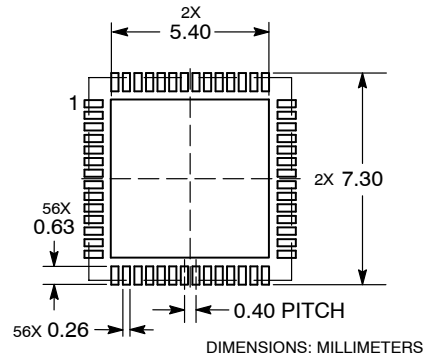| DIM	MILLIMETERS	
	MIN	MAX
A	---	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	7.00 BSC	
D2	5.10	5.30
E	7.00 BSC	
E2	5.10	5.30
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15

**GENERIC
MARKING DIAGRAM***

1 ◯

XXXXXXXXX
XXXXXXXXX
AWLYYWW-
G
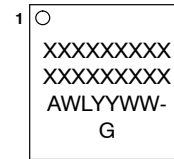
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot " ▪", may or may not be present.

DETAIL A   D2

⊕ | 0.10 Ⓜ | C | A | B

15

29

⊕ | 0.10 Ⓜ | C | A | B

E2

1

56   43

56X L   e

e/2

56X b

⊕ | 0.10 Ⓜ | C | A | B
| 0.05 Ⓜ | C | NOTE 3

BOTTOM VIEW

**RECOMMENDED
SOLDERING FOOTPRINT***

2X
5.40

1

2X 7.30

56X
0.63

56X 0.26   0.40 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WQFN56 7X7, 0.40P		PAGE 1 OF 1